

ABSTRACT OF THE DISCLOSURE

A deposited film forming apparatus is provided which has a power applying electrode disposed above a flat plate type base member grounded, in a vacuum chamber, and a power source for supplying a power to the power applying electrode, the deposited film forming apparatus being constructed to supply the power from the power source to the power applying electrode so as to generate a plasma in a discharge space between the power applying electrode and a substrate disposed in opposition to the power applying electrode in the vacuum chamber and serving as an electrode in a pair with the power applying electrode, thereby decomposing a source gas introduced into the vacuum chamber to form a deposited film on the substrate, wherein the power applying electrode is fixed to the base member with the power applying electrode being isolated from the base member. A deposited film forming method using the apparatus is also provided. This permits the power applying electrode to be fixed to the base member while isolating the power applying electrode from the base member, thereby preventing deformation of the power applying electrode. As a consequence, occurrence of plasma intrusion or abnormal discharge is prevented between the power applying electrode and the base member.